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Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A MEMS package, comprising:
a substrate with a MEMS structure fabricated on a surface of the substrate;
a cover plate bonded to the surface of the substrate by a bond ring;
an inner cavity defined by the substrate, the cover plate and the bond ring; ~~and~~
a fill port defined by the substrate, the cover plate and a breach in the bond ring;
and
a volume of liquid sealed within the inner cavity.
2. Cancelled.
3. (Currently Amended) The MEMS package of Claim 1 2, further comprising:
a seal disposed in the fill port.
4. (Original) The MEMS package of Claim 1, wherein the bond ring comprises at least one of a glass frit, adhesive, eutectic solder, solder mask material, anodic bond, covalent bond, laser weld or Sol-gel material.
5. (Original) The MEMS package of Claim 3, wherein the seal comprises at least one of an adhesive, organic adhesive, epoxy, solder or glass-based sealant.
6. (Original) The MEMS package of Claim 3, wherein the seal comprises a curable adhesive.

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7. (Original) The MEMS package of Claim 1, further comprising:
bond pads for making electrical connections to the MEMS package arranged in
an exposed portion of the substrate.

8. (Currently Amended) A MEMS package adapted for use in a range of
operating temperatures comprising:
a substrate with MEMS circuitry fabricated on a surface of the substrate;
a cover plate bonded to the surface of the substrate by a bond ring;
a fill port defined by the substrate, the cover plate and a breach in the bond ring;
an inner cavity defined by the substrate, the cover plate and the bond ring; and
a liquid fluid sealed within the inner cavity, the liquid fluid having a coefficient of
thermal expansion, wherein the inner cavity has a volume which is small enough so that
expansion of the liquid fluid throughout the range of operating temperatures is
accommodated by deflections of at least the cover plate, substrate and bond ring.

9. (Original) The MEMS package of Claim 8, further comprising:
a seal disposed in the fill port.

10. (Original) The MEMS package of Claim 8, wherein the bond ring
comprises one of a glass frit, adhesive, eutectic solder, solder mask material,
anodic bond, covalent bond, laser weld or Sol-gel material.

11. (Original) The MEMS package of Claim 9, wherein the seal comprises at
least one of an adhesive, organic adhesive, epoxy, solder or glass-based
sealant.

12. (Original) The MEMS package of Claim 9, wherein the seal comprises a
curable adhesive.

13. (Original) The MEMS package of Claim 8, further comprising:

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bond pads arranged in an exposed portion of the surface of the substrate.

14. (Withdrawn) A MEMS assembly comprising:
a substrate with a plurality of MEMS structures fabricated at a plurality of respective die locations on a surface of the substrate;
a cover plate bonded to the surface of the substrate by a plurality of bond rings;
a plurality of inner cavities associated with respective die locations, each being defined by the substrate, the cover plate and one of the plurality of bond rings; and
a plurality of fill ports, each being defined by the substrate, the cover plate and a breach in the one of the plurality of bond rings.

15. (Withdrawn) The MEMS assembly of Claim 14, wherein the cover plate comprises a plurality of openings defining a plurality of exposed portions on the substrate.

16. (Withdrawn) The MEMS assembly of Claim 15, wherein:
a first group of openings define a first group of exposed portions, each of the first group of exposed portions being adjacent a fill port; and
a second group of openings define a second group of exposed portions on the substrate.

17. (Withdrawn) The MEMS assembly of Claim 16, wherein the second group of openings comprise slots.

18. (Withdrawn) The MEMS assembly of Claim 16, further comprising:
a plurality of bond pads on the surface of the substrate arranged in the second group of exposed portions.

19. (Withdrawn) The MEMS assembly of Claim 14, wherein the bond ring comprises one of a glass frit, adhesive, eutectic solder, solder mask material, anodic bond, covalent bond, laser weld or Sol-gel material.

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20. (Withdrawn) A MEMS assembly comprising:
a substrate with a plurality of MEMS structures fabricated at a plurality of respective die locations on a surface of the substrate;
a plurality of cover plates and a plurality of bond rings, each plate being bonded to the substrate by at least one of the bond rings;
a plurality of inner cavities associated with respective die locations, each being defined by the substrate, a respective cover plate and a respective bond ring; and
a plurality of fill ports, each being defined by the substrate, the respective cover plate and a breach in the respective bond ring.

21. (Withdrawn) The MEMS assembly of Claim 20 further comprising:
bond pads arranged in exposed portions on the substrate.

22. (Withdrawn) The MEMS assembly of Claim 14, wherein the bond rings comprise one of a glass frit, adhesive, eutectic solder, solder mask material, anodic bond, covalent bond, laser weld or Sol-gel material.

23. (Withdrawn) A MEMS package comprising:
a substrate with a MEMS structure fabricated on a surface of the substrate;
a cover plate bonded to the surface of the substrate by a bond ring;
an inner cavity defined by the substrate, the cover plate and the bond ring; and
a fill port defined by the substrate, the cover plate and a breach in the bond ring,
wherein the MEMS assembly was singulated from an assembly comprising a plurality of inner cavities.

24. (Withdrawn) The MEMS package of Claim 23, further comprising:
fluid sealed within the inner cavity.

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25. (Withdrawn) The MEMS package of Claim 24, wherein the inner cavity was filled with the fluid prior to singulating the MEMS assembly from the assembly comprising a plurality of inner cavities.

26-47. Cancelled

48. (Currently Amended) A spatial light modulator, comprising:
a substrate with a MEMS mirror array fabricated on a surface of the substrate;
a cover plate bonded to the surface of the substrate by a bond ring;
an inner cavity defined by the substrate, the cover plate and the bond ring; and
a fill port defined by the substrate, the cover plate and a breach in the bond ring;
and
a liquid sealed within the inner cavity.

49. Cancelled.

50. (Currently Amended) The spatial light modulator of Claim 48 ~~49~~, further comprising:
a seal disposed in the fill port.

51. (Original) The spatial light modulator of Claim 48, wherein the bond ring comprises at least one of a glass frit, adhesive, eutectic solder, solder mask material, anodic bond, covalent bond, laser weld or Sol-gel material.

52. (Original) The spatial light modulator of Claim 50, wherein the seal comprises at least one of an adhesive, organic adhesive, epoxy, solder or glass-based sealant.

53. Cancelled.

54. (New) The MEMS package according to claim 1.

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wherein the bond ring comprises at least one of a glass frit, adhesive, eutectic solder, anodic bond, covalent bond, laser weld or Sol-gel material.

55. (New) The MEMS package according to claim 1, wherein the seal comprises at least one of an adhesive, organic adhesive, epoxy, or glass-based sealant.

56. (New) The MEMS package according to claim 8, wherein the bond ring comprises one of a glass frit, adhesive, eutectic solder, anodic bond, covalent bond, laser weld or Sol-gel material.

57. (New) The MEMS package according to claim 8, wherein the seal comprises at least one of an adhesive, organic adhesive, epoxy, or glass-based sealant.